

Flash Memory Summit Market Research

Scott Jacobson Flash Memory Summit 5 – 7 August 2014

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- NAND flash growth
- Verification challenges
- Alternatives
- Future

Demand forecast by application

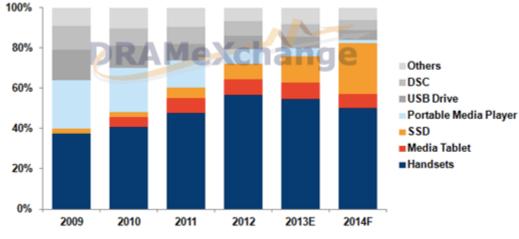


Table-3 2009-2014F NAND Flash Demand Dynamics

Source: DRAMeXchange, Nov., 2013



Source : DRAMeXchange, Dec., 2013

Growth in SSDs adding to the consumption growth of handsets and tablets



Demand forecast

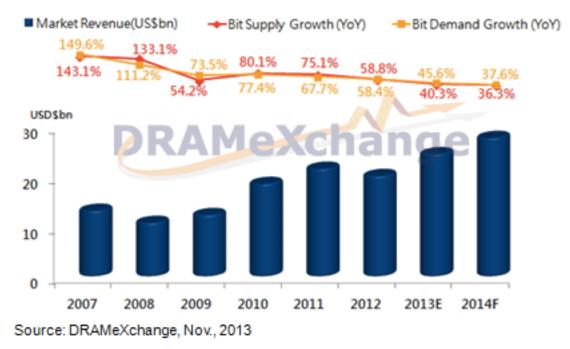
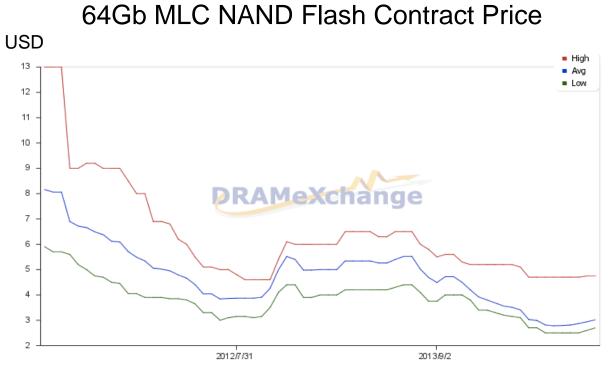


Table-1 2007-2014F NAND Flash Market Value and Bit Growth

NAND flash growth trends are worldwide

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Pricing pressure



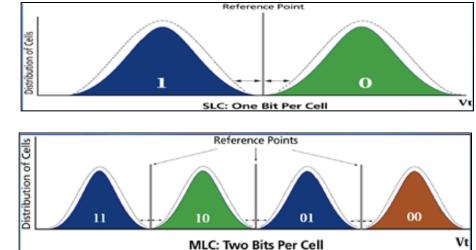
Source: DRAMeXchange, July 2014

At the same time that demand is increasing, prices are stabilizing

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MLC vs. SLC

- Growth pressures for higher density and higher performance has driven the transition from SLC to MLC
- This transition does not come at no cost, increased capacity also increases sensitivity to errors





Technology scaling and 3D NAND

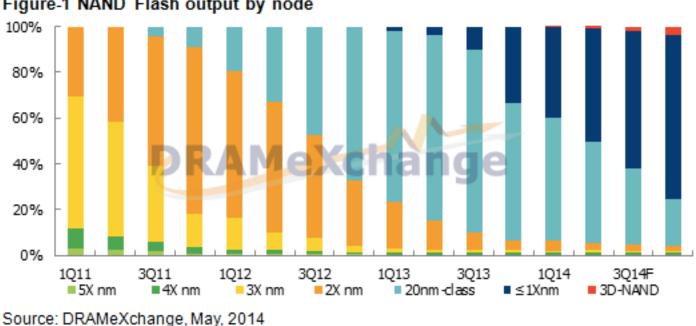


Figure-1 NAND Flash output by node

Scaling limitations driving development—Expected to peak in 2H 2015

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Verification challenges

- To effectively verify ECC performance in simulation, one needs to be able to:
 - Inject errors into memories during simulation
 - Set assertions
 - Memory
 - Data
 - Parity checking
 - Explore memory space
 - Width expansion
 - Depth expansion
 - Interleaving
 - Address scrambling
 - Internal memory register access

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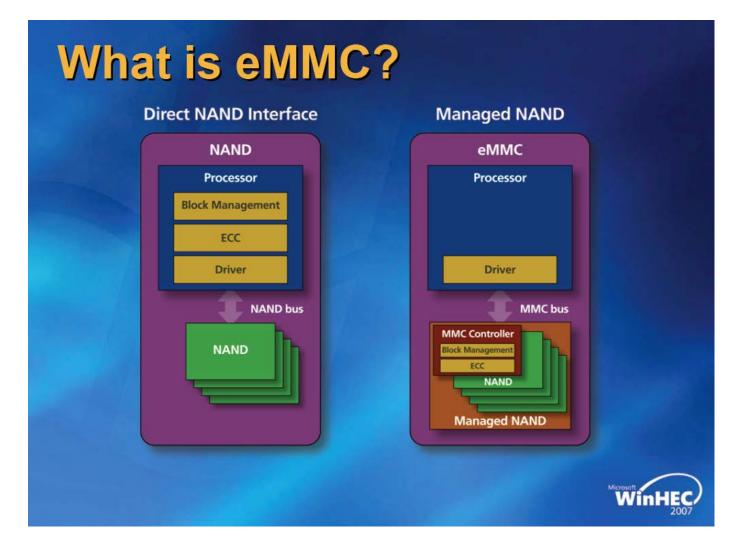
What's next?

Managed NAND solutions

- Vendor and technology independence
 - ECC
 - Partial page program operations
 - Commands and interfaces
- eMMC 4.5
- UFS



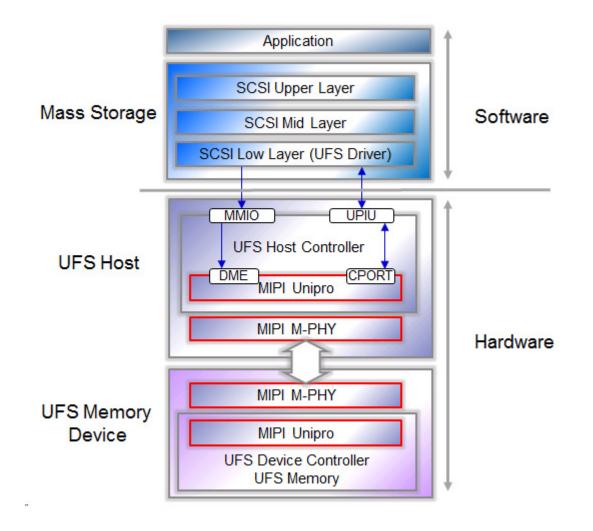
eMMC





UFS..

Universal Flash Storage (UFS) System Architecture



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Trends

- ECC approaches continue to be more complex and must be used judiciously based on application targets
- High IOPS application requirements continue the drive for higher transfer rates
- Managed NAND solutions becoming more complex in implementation but more standardized in approaches
- 3D NAND



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